

# XP132A0340SR



Power MOS FET

## ◆P-Channel Power MOS FET

## ◆DMOS Structure

## ◆Low On-State Resistance: 0.04Ω (max)

## ◆Ultra High-Speed Switching

## ◆SOP-8 Package

## ■General Description

The XP132A0340SR is a P-Channel Power MOS FET with low on-state resistance and ultra high-speed switching characteristics.

Because high-speed switching is possible, the IC can be efficiently set thereby saving energy.

The small SOP-8 package makes high density mounting possible.

## ■Applications

- Notebook PCs
- Cellular and portable phones
- On-board power supplies
- Li-ion battery systems

## ■Features

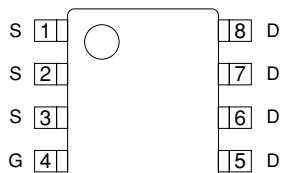
**Low on-state resistance** :  $R_{ds(on)}=0.04\Omega(V_{gs}=-4.5V)$   
:  $R_{ds(on)}=0.06\Omega(V_{gs}=-2.5V)$

**Ultra high-speed switching**

**Operational Voltage** : -4.5V

**High density mounting** : SOP-8

## ■Pin Configuration

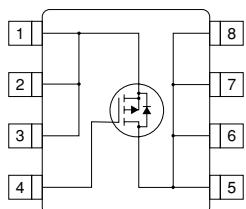


SOP-8  
(TOP VIEW)

## ■Pin Assignment

PIN NUMBER	PIN NAME	FUNCTION
1 ~ 3	S	Source
4	G	Gate
5 ~ 8	D	Drain

## ■Equivalent Circuit



P-Channel MOS FET  
(1 device built-in)

## ■Absolute Maximum Ratings

T<sub>a</sub>=25°C

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PARAMETER	SYMBOL	RATINGS	UNITS
Drain-Source Voltage	V <sub>dss</sub>	-20	V
Gate-Source Voltage	V <sub>gss</sub>	±8	V
Drain Current (DC)	I <sub>d</sub>	-7	A
Drain Current (Pulse)	I <sub>dp</sub>	-25	A
Reverse Drain Current	I <sub>dr</sub>	-7	A
Continuous Channel Power Dissipation (note)	P <sub>d</sub>	2.5	W
Channel Temperature	T <sub>ch</sub>	150	°C
Storage Temperature	T <sub>stg</sub>	-55~150	°C

Note: When implemented on a glass epoxy PCB

# XP132A0340SR

## ■ Electrical Characteristics

### DC Characteristics

T<sub>a</sub>=25°C

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
Drain Cut-off Current	I <sub>dss</sub>	V <sub>ds</sub> =-20V, V <sub>gs</sub> =0V			-10	μA
Gate-Source Leakage Current	I <sub>gss</sub>	V <sub>gs</sub> =±8V, V <sub>ds</sub> =0V			±1	μA
Gate-Source Cut-off Voltage	V <sub>gs(off)</sub>	I <sub>d</sub> =-1mA, V <sub>ds</sub> =-10V	-0.5		-1.2	V
Drain-Source On-state Resistance (note)	R <sub>ds(on)</sub>	I <sub>d</sub> =-4A, V <sub>gs</sub> =-4.5V		0.03	0.04	Ω
		I <sub>d</sub> =-4A, V <sub>gs</sub> =-2.5V		0.045	0.06	Ω
Forward Transfer Admittance (note)	Y <sub>fs</sub>	I <sub>d</sub> =-4A, V <sub>ds</sub> =-10V		13		S
Body Drain Diode Forward Voltage	V <sub>f</sub>	I <sub>f</sub> =-7A, V <sub>gs</sub> =0V		-0.85	-1.1	V

Note: Effective during pulse test.

### Dynamic Characteristics

T<sub>a</sub>=25°C

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
Input Capacitance	C <sub>iss</sub>	V <sub>ds</sub> =-10V, V <sub>gs</sub> =0V f=1MHz		2000		pF
Output Capacitance	C <sub>oss</sub>			1100		pF
Feedback Capacitance	C <sub>rss</sub>			550		pF

### Switching Characteristics

T<sub>a</sub>=25°C

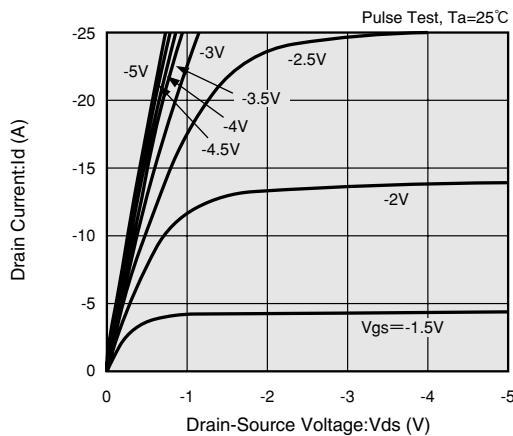
PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
Turn-on Delay Time	t <sub>d</sub> (on)	V <sub>gs</sub> =-5V, I <sub>d</sub> =-4A V <sub>dd</sub> =-10V		15		ns
Rise Time	t <sub>r</sub>			25		ns
Turn-off Delay Time	t <sub>d</sub> (off)			75		ns
Fall Time	t <sub>f</sub>			50		ns

### Thermal Characteristics

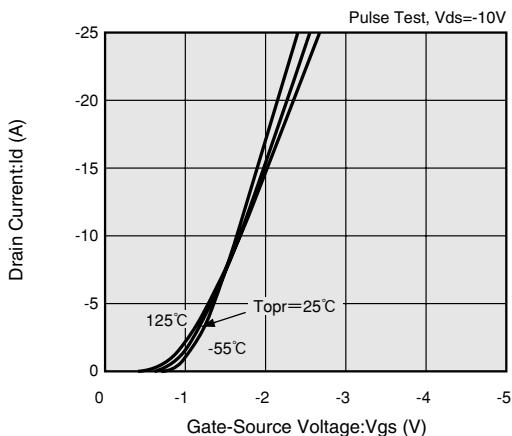
PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
Thermal Resistance (channel-ambience)	R <sub>th</sub> (ch-a)	Implement on a glass epoxy resin PCB		50		°C/W

## ■ Typical Performance Characteristics

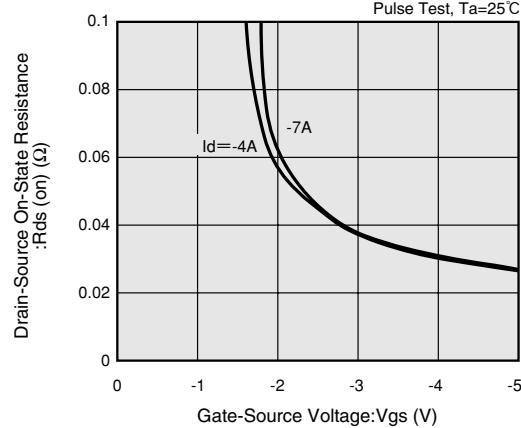
DRAIN CURRENT vs. DRAIN-SOURCE VOLTAGE



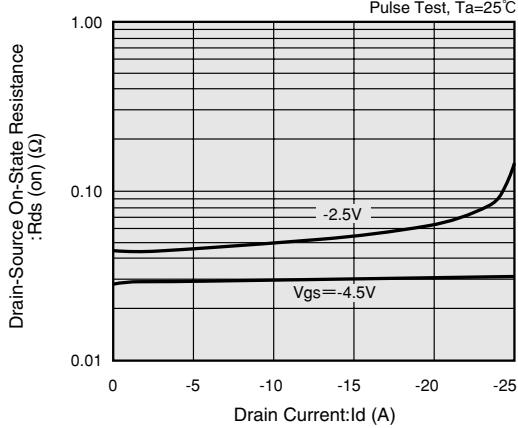
DRAIN CURRENT vs. GATE-SOURCE VOLTAGE



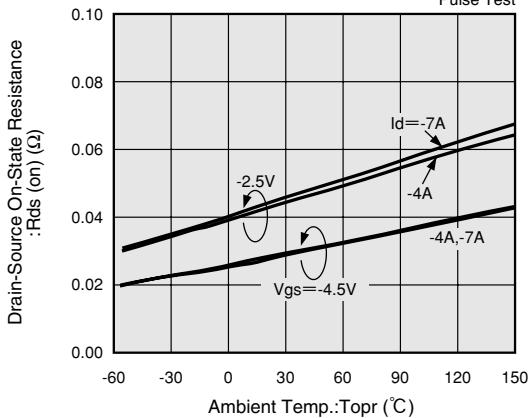
DRAIN-SOURCE ON-STATE RESISTANCE vs. GATE-SOURCE VOLTAGE



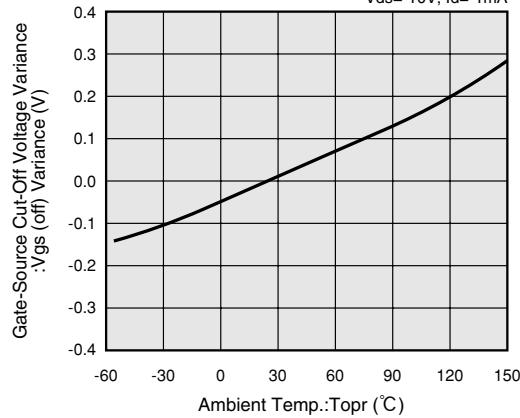
DRAIN-SOURCE ON-STATE RESISTANCE vs. DRAIN CURRENT



DRAIN-SOURCE ON-STATE RESISTANCE vs. AMBIENT TEMPERATURE

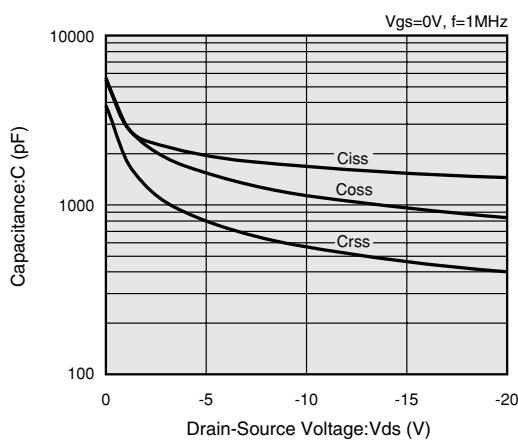


GATE-SOURCE CUT-OFF VOLTAGE VARIANCE vs. AMBIENT TEMPERATURE

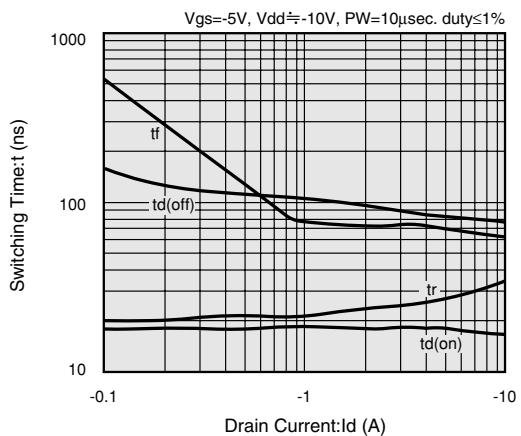


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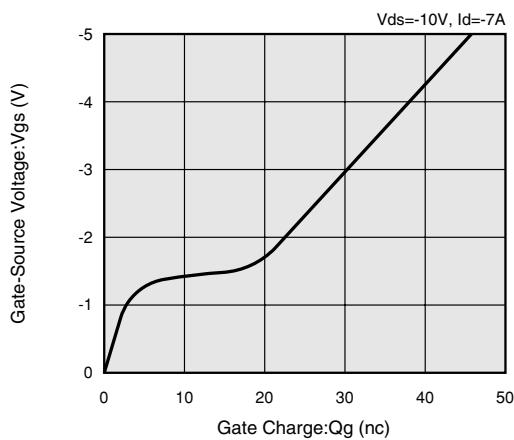
CAPACITANCE vs. DRAIN-SOURCE VOLTAGE



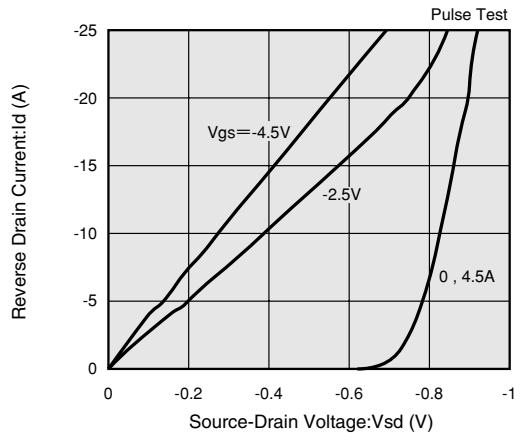
SWITCHING TIME vs. DRAIN CURRENT



GATE-SOURCE VOLTAGE vs. GATE CHARGE



REVERSE DRAIN CURRENT  
vs. SOURCE-DRAIN VOLTAGE



STANDARDIZED TRANSITION THERMAL RESISTANCE vs. PULSE WIDTH

